

MPC7410 RISC Microprocessor Hardware Specifications Addendum for the MPC7410THX nnn LE Series

This document describes part-number-specific changes to recommended operating conditions and revised electrical specifications, as applicable, from those described in the *MPC7410 RISC Microprocessor Hardware Specifications* (Document No. MPC7410EC).

Specifications provided in this document supersede those in the *MPC7410 RISC Microprocessor Hardware Specifications*, Rev. 1 or later, for the part numbers listed in [Table A](#) only. Specifications not addressed herein are unchanged. Because this document is frequently updated, refer to <http://www.freescale.com> or to your Freescale sales office for the latest version.

Note that headings and table numbers in this document are not consecutively numbered. They are intended to correspond to the heading or table affected in the general hardware specification.

Part numbers addressed in this document are listed in [Table A](#). For more detailed ordering information [Table 17](#)

Freescale Part Numbers Affected:

MPC7410THX400LE
MPC7410THX450LE
MPC7410THX500LE

This document contains information on a new product. Specifications and information herein are subject to change without notice.

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Table A. Part Numbers Addressed by this Data Sheet

Freescale Part Number	Operating Conditions				Significant Differences from Hardware Specification
	CPU Frequency (MHz)	V _{DD}	T _J (°C)	OV _{DD} (V)	
MPC7410THX500LE	500	1.8 V ±100 mV	-40 to 105	1.8/2.5/3.3	Extended temperature range. For all DC/AC specifications not mentioned in this document, please refer to the MPC7410RX500LE specifications in the <i>MPC7410 RISC Microprocessor Hardware Specifications</i> .
MPC7410THX450LE	450	1.8 V ±100 mV	-40 to 105	1.8/2.5/3.3	Extended temperature range. For all DC/AC specifications not mentioned in this document, please refer to the MPC7410RX450LE specifications in the <i>MPC7410 RISC Microprocessor Hardware Specifications</i> .
MPC7410THX400LE	400	1.8 V ±100 mV	-40 to 105	1.8/2.5/3.3	Extended temperature range. For all DC/AC specifications not mentioned in this document, please refer to the MPC7410RX400LE specifications in the <i>MPC7410 RISC Microprocessor Hardware Specifications</i> .

4.1 DC Electrical Characteristics

Table 3 provides the recommended operating conditions for the MPC7410 part numbers described herein.

Table 3. Recommended Operating Conditions

Characteristic	Symbol	Recommended Value	Unit	Notes
Die-junction temperature	T _j	-40 to 105	°C	

Note: See *MPC7410 RISC Microprocessor Hardware Specifications*.

9 Document Revision History

Table 16 provides a revision history for this document.

Table 16. Document Revision History

Revision	Date	Substantive Changes(s)
0.1	4/20/2005	Document template update
		Document ID change from MPC7410THXLEPNS for Part Number Specification to MPC7410ECS08AD for Hardware Specification Addendum.
0	10/2003	Initial release.

10 Ordering Information

10.1 Part Numbers Addressed by this Specification

Table 17 provides the ordering information for the MPC7410 part described in this document.

Table 17. Part Marking Nomenclature

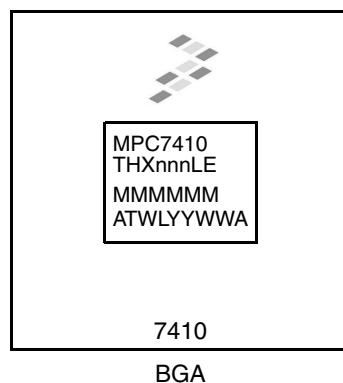
Product Code	Part Identifier	Process Descriptor	Package	Processor Frequency ¹	Application Modifier	Revision Level
MPC	7410	T: -40 to 105°C	HX = HCTE	400 450 500	L: 1.8 V ±100 mV	E: 1.4; PVR = 800C 1104

Note:

1.Processor core frequencies supported by parts addressed by this specification only. Parts addressed by other specifications may support other maximum core frequencies.

10.3 Part Marking

Parts are marked as the example shown in Figure 26.



Notes:

nnn is the speed grade of the part.

MMMMMM is the 6-digit mask number.

ATWLYYWWA is the traceability code.

CCCCC is the country of assembly. This space is left blank if parts are assembled in the United States.

Figure 26. Part Marking for BGA Device

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